

June 1988 Revised July 1999

### 74F219

# 64-Bit Random Access Memory with 3-STATE Outputs

#### **General Description**

The 74F219 is a high-speed 64-bit RAM organized as a 16-word by 4-bit array. Address inputs are buffered to minimize loading and are fully decoded on-chip. The outputs are 3-STATE and are in the high-impedance state whenever the Chip Select (CS) input is HIGH. The outputs are active only in the Read mode. This device is similar to the 74F189 but features non-inverting, rather than inverting, data outputs.

#### **Features**

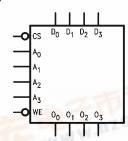
- 3-STATE outputs for data bus applications
- Buffered inputs minimize loading
- Address decoding on-chip
- Diode clamped inputs minimize ringing
- Available in SOIC (300 mil only)

### **Ordering Code:**

Order Number	Package Number	Package Description
74F219SC	M16B	16-Lead Small Outline Intergrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F219SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F219PC	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

## **Logic Symbol**



## **Connection Diagram**



# **Unit Loading/Fan Out**

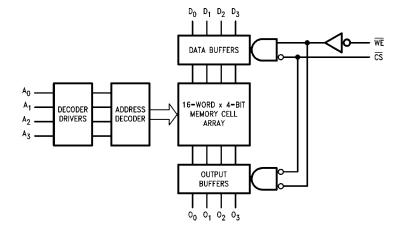
Pin Names	Decemention	U.L.	Input I <sub>IH</sub> /I <sub>IL</sub>		
Pin Names	Description	HIGH/LOW	Output I <sub>OH</sub> /I <sub>OL</sub>		
A <sub>0</sub> -A <sub>3</sub>	Address Inputs	1.0/1.0	20 μA/–0.6 mA		
CS	Chip Select Input (Active LOW)	1.0/2.0	20 μA/–1.2 mA		
WE	Write Enable Input (Active LOW)	1.0/1.0	20 μA/-0.6 mA		
D <sub>0</sub> -D <sub>3</sub>	Data Inputs	1.0/1.0	20 μA/-0.6 mA		
O <sub>0</sub> -O <sub>3</sub>	3-STATE Data Outputs	150/40 (33.3)	-3 mA/24 mA (20 mA)		

#### **Function Table**

Inputs		Operation	Condition of Outputs			
cs	WE	Operation	Condition of Outputs			
L	L	Write	High Impedance			
L	Н	Read	True Stored Data			
Н	X	Inhibit	High Impedance			

$$\begin{split} & H = HIGH \ Voltage \ Level \\ & L = LOW \ Voltage \ Level \\ & X = Immaterial \end{split}$$

## **Block Diagram**



#### **Absolute Maximum Ratings**(Note 1)

# Recommended Operating Conditions

 $\begin{array}{ll} \mbox{Storage Temperature} & -65\mbox{°C to } +150\mbox{°C} \\ \mbox{Ambient Temperature under Bias} & -55\mbox{°C to } +125\mbox{°C} \\ \end{array}$ 

Junction Temperature under Bias -55°C to +150°C V<sub>CC</sub> Pin Potential to Ground Pin -0.5V to +7.0V

Input Voltage (Note 2) -0.5 V to +7.0 VInput Current (Note 2) -30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with  $V_{CC} = 0V$ )

Standard Output -0.5V to V<sub>CC</sub>

Current Applied to Output

in LOW State (Max)  $\qquad \qquad \text{twice the rated I}_{\text{OL}} \, (\text{mA})$ 

Free Air Ambient Temperature  $0^{\circ}\text{C to } +70^{\circ}\text{C}$  Supply Voltage +4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation

under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

#### **DC Electrical Characteristics**

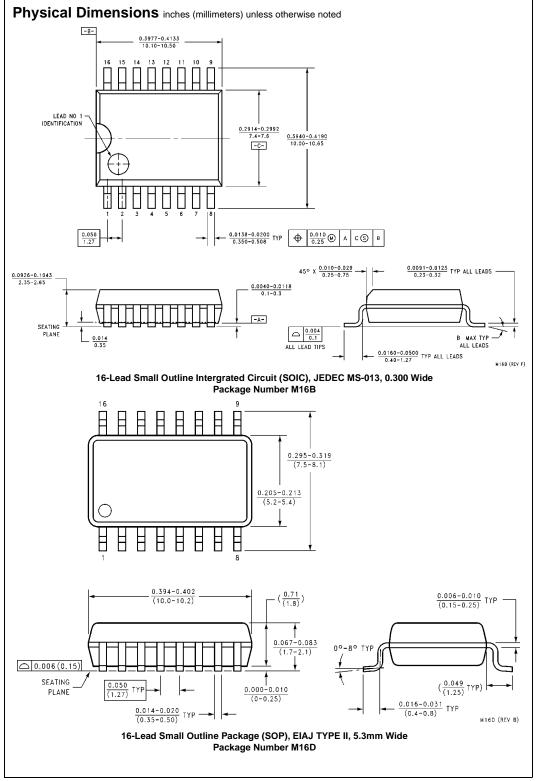
Symbol	Parameter		Min	Тур	Max	Units	v <sub>cc</sub>	Conditions	
V <sub>IH</sub>	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal	
V <sub>IL</sub>	Input LOW Voltage				0.8	V		Recognized as a LOW Signal	
V <sub>CD</sub>	Input Clamp Diode Voltage				-1.2	V	Min	I <sub>IN</sub> = -18 mA	
V <sub>OH</sub>	Output HIGH	10% V <sub>CC</sub>	2.5					I <sub>OH</sub> = -1 mA	
	Voltage	10% V <sub>CC</sub>	2.4			V	Min	$I_{OH} = -3 \text{ mA}$	
		$5\% V_{CC}$	2.7			V	IVIIII	$I_{OH} = -1 \text{ mA}$	
		$5\% V_{CC}$	2.7					$I_{OH} = -3 \text{ mA}$	
V <sub>OL</sub>	Output LOW	10% V <sub>CC</sub>			0.5	V	Min	I <sub>OL</sub> = 24 mA	
	Voltage				0.5	V	IVIIII	10L - 24 IIIA	
I <sub>IH</sub>	Input HIGH				5.0	μА	Mov	V <sub>IN</sub> = 2.7V	
	Current				5.0	μА	Max	VIN - 2.1 V	
I <sub>BVI</sub>	Input HIGH Current				7.0	μА	Max	V <sub>IN</sub> = 7.0V	
	Breakdown Test				7.0				
I <sub>CEX</sub>	Output HIGH			,	50	μА	Max	$V_{OLIT} = V_{CC}$	
	Leakage Current				30	μΛ	IVICA	v001 − vCC	
V <sub>ID</sub>	Input Leakage		4.75			V	0.0	$I_{ID} = 1.9 \mu A$	
	Test		4.73			V	0.0	All Other Pins Grounded	
I <sub>OD</sub>	Output Leakage				3.75	^	0.0	V <sub>IOD</sub> = 150 mV	
	Circuit Current				3.73	μА	0.0	All Other Pins Grounded	
I <sub>IL</sub>	Input LOW				-0.6	mA	Max	$V_{IN} = 0.5V (A_n, \overline{WE}, D_n)$	
	Current				-1.2			$V_{IN} = 0.5V (\overline{CS})$	
I <sub>OZH</sub>	Output Leakage Current				50	μΑ	Max	V <sub>OUT</sub> = 2.7V	
I <sub>OZL</sub>	Output Leakage Current				-50	μΑ	Max	V <sub>OUT</sub> = 0.5V	
Ios	Output Short-Circuit Current		-60		-150	mA	Max	V <sub>OUT</sub> = 0V	
I <sub>ZZ</sub>	Bus Drainage Test				500	μΑ	0.0V	V <sub>OUT</sub> = 5.25V	
I <sub>CC</sub>	Power Supply Current			37	55	mA	Max		

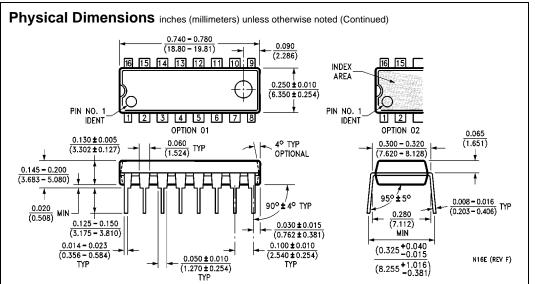
# **AC Electrical Characteristics**

		$T_{A} = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_{L} = 50 \text{ pF}$			$T_{A} = -55 ^{\circ} C \text{ to } +125 ^{\circ} C$ $V_{CC} = +5.0 V$ $C_{L} = 50 \text{ pF}$		$T_A = 0$ °C to +70°C $V_{CC} = +5.0V$ $C_L = 50 \text{ pF}$		Units
Symbol	Parameter								
		Min	Тур	Max	Min	Max	Min	Max	
t <sub>PLH</sub>	Access Time, HIGH or LOW	10.0	18.5	26.0	9.0	32.0	10.0	27.0	ns
t <sub>PHL</sub>	A <sub>n</sub> to O <sub>n</sub>	8.0	13.5	19.0	8.0	23.0	8.0	20.0	115
t <sub>PZH</sub>	Access Time, HIGH or LOW	3.5	6.0	8.5	3.5	10.5	3.5	9.5	ns
t <sub>PZL</sub>	CS to O <sub>n</sub>	5.0	9.0	13.0	5.0	15.0	5.0	14.0	
t <sub>PHZ</sub>	Disable Time, HIGH or LOW	2.0	4.0	6.0	2.0	8.0	2.0	7.0	
t <sub>PLZ</sub>	CS to O <sub>n</sub>	3.0	5.5	8.0	2.5	10.0	3.0	9.0	
t <sub>PZH</sub>	Write Recovery Time	6.5	20.0	28.0	6.5	37.5	6.5	29.0	ns
t <sub>PZL</sub>	HIGH or LOW, WE to On	6.5	11.0	15.5	6.5	17.5	6.5	16.5	
t <sub>PHZ</sub>	Disable Time, HIGH or LOW	4.0	7.0	10.0	3.5	12.0	4.0	11.0	
t <sub>PLZ</sub>	WE to O <sub>n</sub>	5.0	9.0	13.0	5.0	15.0	5.0	14.0	

# **AC Operating Requirements**

		$T_A = +25$ °C $V_{CC} = +5.0$ V		$T_A = -55$ °C to +125°C $V_{CC} = +5.0V$		$T_A = 0$ °C to +70°C $V_{CC} = +5.0V$		Units
Symbol	Parameter							
		Min	Max	Min	Max	Min	Max	
t <sub>S</sub> (H)	Setup Time, HIGH or LOW	0		0		0		ns
$t_S(L)$	A <sub>n</sub> to WE	0		0		0		
t <sub>H</sub> (H)	Hold Time, HIGH or LOW	2.0		2.0		2.0		
$t_H(L)$	A <sub>n</sub> to WE	2.0		2.0		2.0		
t <sub>S</sub> (H)	Setup Time, HIGH or LOW	10.0		11.0		10.0		ns
$t_S(L)$	D <sub>n</sub> to WE	10.0		11.0		10.0		
t <sub>H</sub> (H)	Hold Time, HIGH or LOW	0		2.0		0		
$t_H(L)$	D <sub>n</sub> to WE	0		2.0		0		
t <sub>S</sub> (L)	Setup Time, LOW	0		0		0		ns
	CS to WE							
t <sub>H</sub> (L)	Hold Time, LOW	6.0		7.5		6.0		
	CS to WE							
t <sub>W</sub> (L)	WE Pulse Width, LOW	6.0		15.0		6.0		ns





16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N16E

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